

EVG WORKSHOP/TECHNOLOGY DAY, NEW DELHI

Photolithography And Bonding Technologies

CSIR-National Physical Laboratory

Dr KS Krishnan Marg, South Patel Nagar
Pusa, New Delhi

December 18, 2017 | 9:00-16:00 hrs



NATIONAL
PHYSICAL
LABORATORY

Tesscorn

9:00 Registration

10:00 Welcome & Introduction

Welcome talk by Dr. C.M.S. Rauthan, Chairperson, Silicon Solar Group, NPL
Introduction by Roland Haidinger, Regional Sales Manager, EV Group

SESSION 1:

MASK ALIGNER, RESIST PROCESSING AND NANOIMPRINT LITHOGRAPHY

10:15 Mask Alignment in R&D and Manufacturing Applications; Novel and Upcoming Technologies
[Frank Bögelsack, EV Group](#)

11:10 Resist Processing Various Applications and Coaters, Developers and Cleaners
[Martin Schmidbauer, EV Group](#)

11:45 Tea Break

12:00 Nano Imprint Lithography Processes, Application and Hot Embossing
[Anneliese Pönninger, Frank Bögelsack and Martin Schmidbauer, EV Group](#)

12:40-14:00 Lunch Break

SESSION 2:

BONDING TECHNOLOGIES

14:00 Permanent Bonding Processes (Metal, Anodic, Adhesive, Glass Frit) and Application Areas and Optically Aligned Bonding
[Vineeth Reddy Bijjam and Anneliese Pönninger, EV Group](#)

14:50 Direct Bonding/Fusion Bonding Processes, Applications and Plasma Activation and Cleaning
[Anneliese Pönninger and Martin Schmidbauer, EV Group](#)

15:20 Tea Break

15:35 Temporary Bonding/Debonding Processes and Materials (Focus Thermoplastic adhesives), Equipment Configurations for R&D and Manufacturing (Coaters, Bonders, Debonders, Cleaners)
[Vineeth Reddy Bijjam and Martin Schmidbauer, EV Group](#)

Interested researchers and students kindly [click here to register before November 30, 2017.](#)

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No registration fee is charged.

Registration is Limited

Snacks, Tea, Coffee, and Lunch are included.

Accommodation and transportation is to be taken care by the participants

Speakers Profile:

Anneliese Pönninger

Business Development Manager at EV Group with a focus in bonding technologies. She is project manager for EU and nationally funded cooperative projects in different technology and application areas. She has more than 20 years of professional experience in electrical engineering, materials science and aerospace technology both in industry and research establishments. Pönninger has a Master degree in applied physics from the University of Technology, Vienna.

Frank Bögelsack

Product Manager for metrology tools and alignment systems at EVG. He graduated at the University of Applied Science in Leipzig, Germany in the area of energy technology. With his multifunctional team he is responsible for improving the existing tools as well as extend the tool portfolio for new applications. From 2001 thru 2016 he worked in the aeronautics and space business in several countries before joining EVG in 2016 as the product manager for metrology and alignment tools.

Vineeth Reddy Bijjam

Program Manager for development and pilot line manufacturing projects in the area of Wafer Bonding and Nano Imprint Lithography. His expertise include Metal Bonding, Anodic Bonding, wafer to wafer alignment, process development, Pilot line production, High Volume manufacturing. He served as a research associate in European funded projects for designing and fabrication of MEMS microphones & Microfluidic applications at 'Institute of Applied Research' in the Furtwangen University of Applied Science, Germany.

Martin Schmidbauer

Product Manager for resist processing systems at EV Group headquarters in St. Florian, Austria. He graduated in mechatronic engineering at the Johannes Kepler University in Linz. His current work covers all areas of resist processing systems such as spin coating and spray coating. He has co-authored several papers in these areas.

Roland Haidinger

Regional Sales Manager Asia/ Pacific and in this role responsible for all Sales related activities related to the Southeast Asia market. He graduated in 2000 from the Engineering College Voecklabruck in Upper Austria, in the area of Mechanical Engineering. From 2001 thru 2016 he worked in the Aviation Industry in Austria and Asia before joining EVG in 2017 as the Regional Sales Manager. Roland is in his function also the Regional Sales Manager for the Indian market and therefore Key Account Manager for all EVG customers from India.